

US00D846512S

(12) **United States Design Patent** (10) **Patent No.:** **US D846,512 S**
Nishio et al. (45) **Date of Patent:** **** Apr. 23, 2019**

(54) **OPTICAL SEMICONDUCTOR ELEMENT**

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(71) Applicant: **HAMAMATSU PHOTONICS K.K.**,
Hamamatsu-shi, Shizuoka (JP)

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(72) Inventors: **Fumitaka Nishio**, Hamamatsu (JP);
Makio Kume, Hamamatsu (JP)

Primary Examiner — Rhea Shields

(74) *Attorney, Agent, or Firm* — Drinker Biddle & Reath
LLP

(73) Assignee: **HAMAMATSU PHOTONICS K.K.**,
Hamamatsu-shi, Shizuoka (JP)

(57) **CLAIM**

(**) Term: **15 Years**

The ornamental design for an optical semiconductor ele-
ment, as shown and described.

(21) Appl. No.: **29/645,564**

DESCRIPTION

(22) Filed: **Apr. 27, 2018**

Related U.S. Application Data

(62) Division of application No. 35/502,664, filed on Sep.
21, 2016 (U.S. filing date under 35 U.S.C. 384), and
(Continued)

(30) **Foreign Application Priority Data**

Mar. 24, 2016 (JP) 2016-006367
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(51) **LOC (11) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/180**

(58) **Field of Classification Search**

USPC D13/180, 134; D14/371; D9/737;
D26/122, 120, 141, 118, 1; 257/98, 88,
257/100, 87; 524/307; 372/45.01
(Continued)

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(Continued)

FIG. 1 is a top perspective view of an optical semiconductor
element of the present invention.

FIG. 2 is a bottom perspective view of the optical semicon-
ductor element of FIG. 1.

FIG. 3 is a front view of the optical semiconductor element
of FIG. 1.

FIG. 4 is a back view of the optical semiconductor element
of FIG. 1.

FIG. 5 is a top view of the optical semiconductor element of
FIG. 1.

FIG. 6 is a bottom view of the optical semiconductor
element of FIG. 1.

FIG. 7 is a left view of the optical semiconductor element of
FIG. 1.

FIG. 8 is a right view of the optical semiconductor element
of FIG. 1.

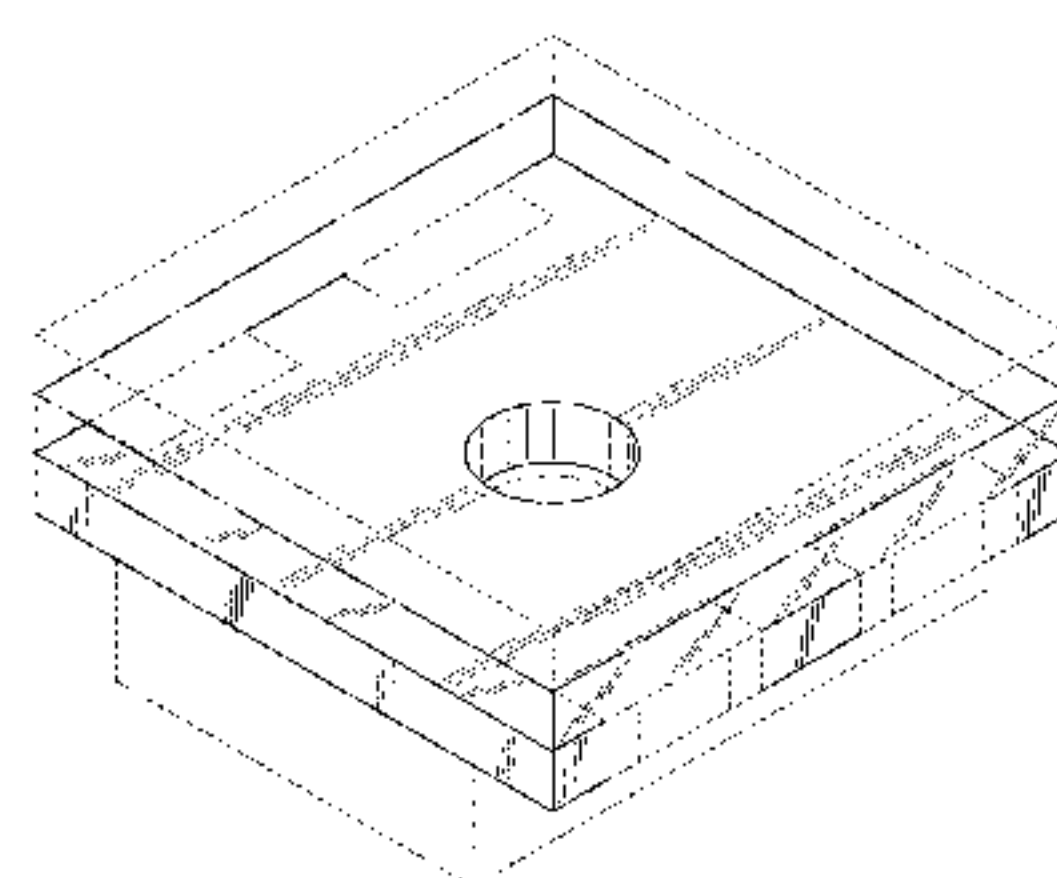
FIG. 9 is a sectional view taken along the line 9-9 of the
optical semiconductor element of FIG. 5.

FIG. 10 is a sectional view taken along the line 10-10 of the
optical semiconductor element of FIG. 5; and,

FIG. 11 is a reference perspective view of the optical
semiconductor element of FIG. 1 in use, wherein the optical
semiconductor element is attached to a mount board, which
is for illustrative purpose only and form no part of the
claimed design.

The dash-dot-dash broken lines are for the purpose of
illustrating the boundaries of the claimed design.

(Continued)



The evenly spaced broken lines are for the purpose of illustrating environment only and form no part of the claimed design.

1 Claim, 11 Drawing Sheets

Related U.S. Application Data

having an international filing date of Sep. 21, 2016, now Pat. No. Des. 826,184.

(58) Field of Classification Search

CPC ... H01L 33/62; H01L 33/486; H01L 27/1463;
H01L 25/0753; H01L 33/44; C08G 77/04;
B29C 45/0001; C08K 5/13; H01S 5/162;
C08L 83/04

See application file for complete search history.

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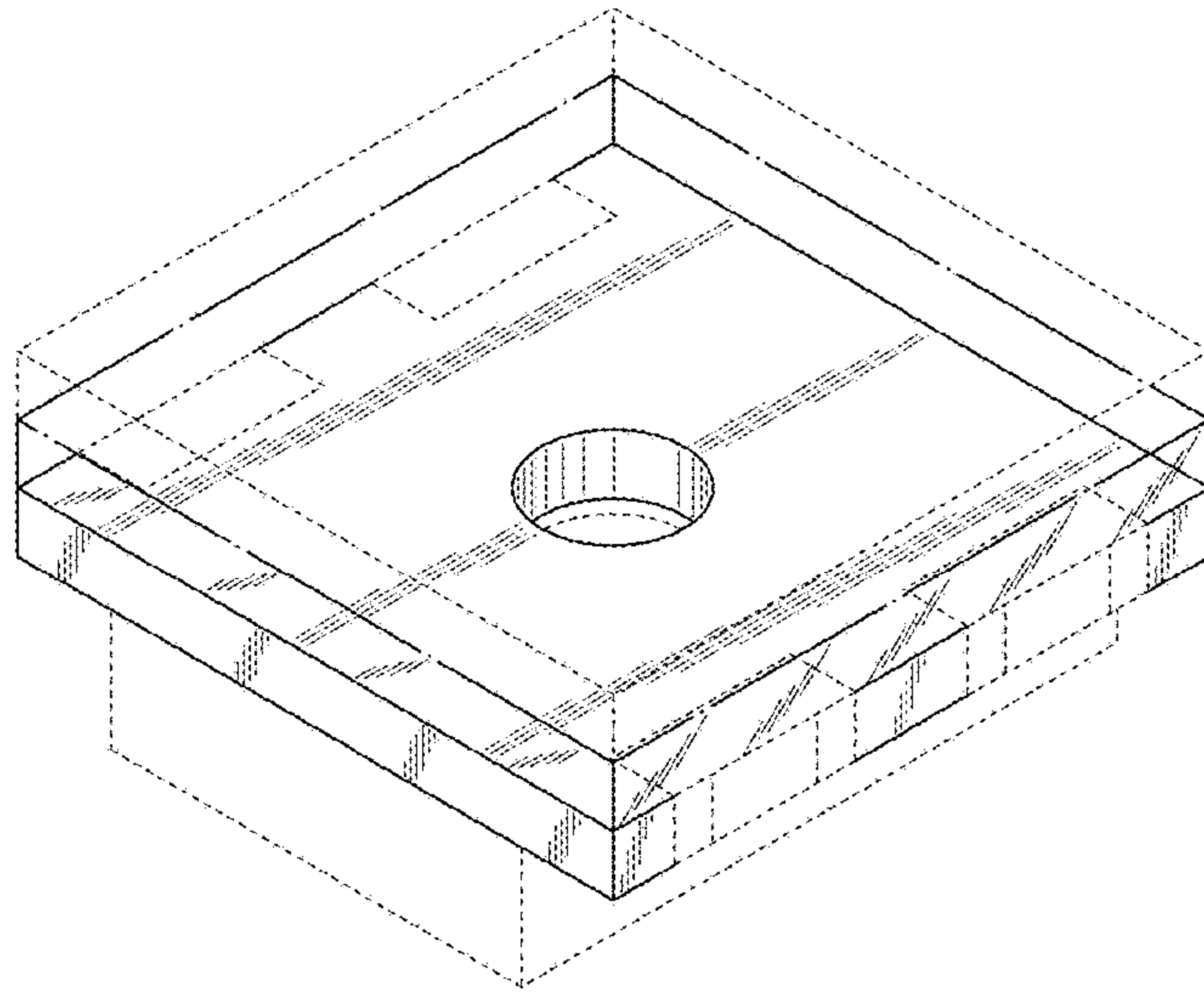


FIG. 1

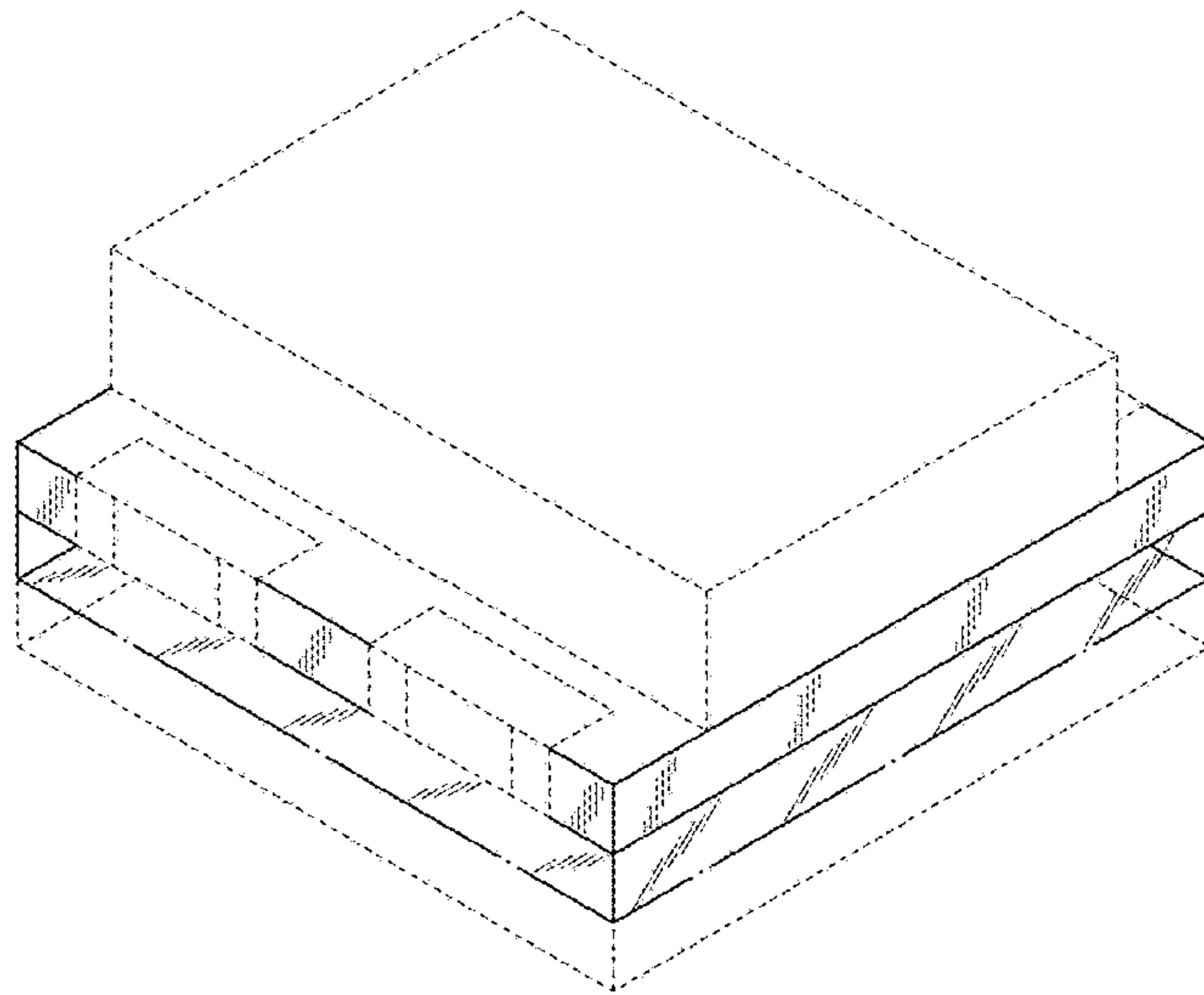


FIG. 2

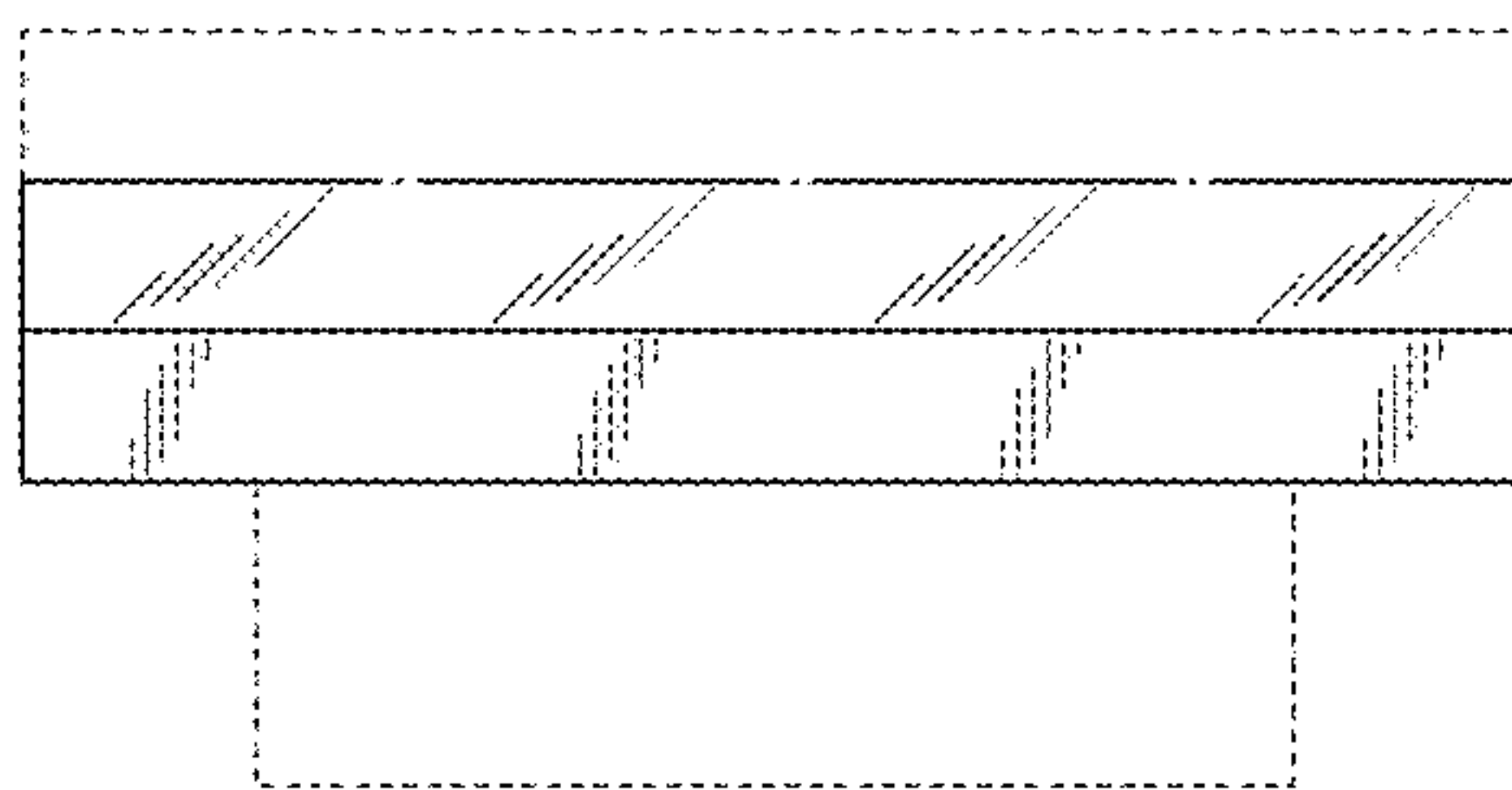


FIG. 3

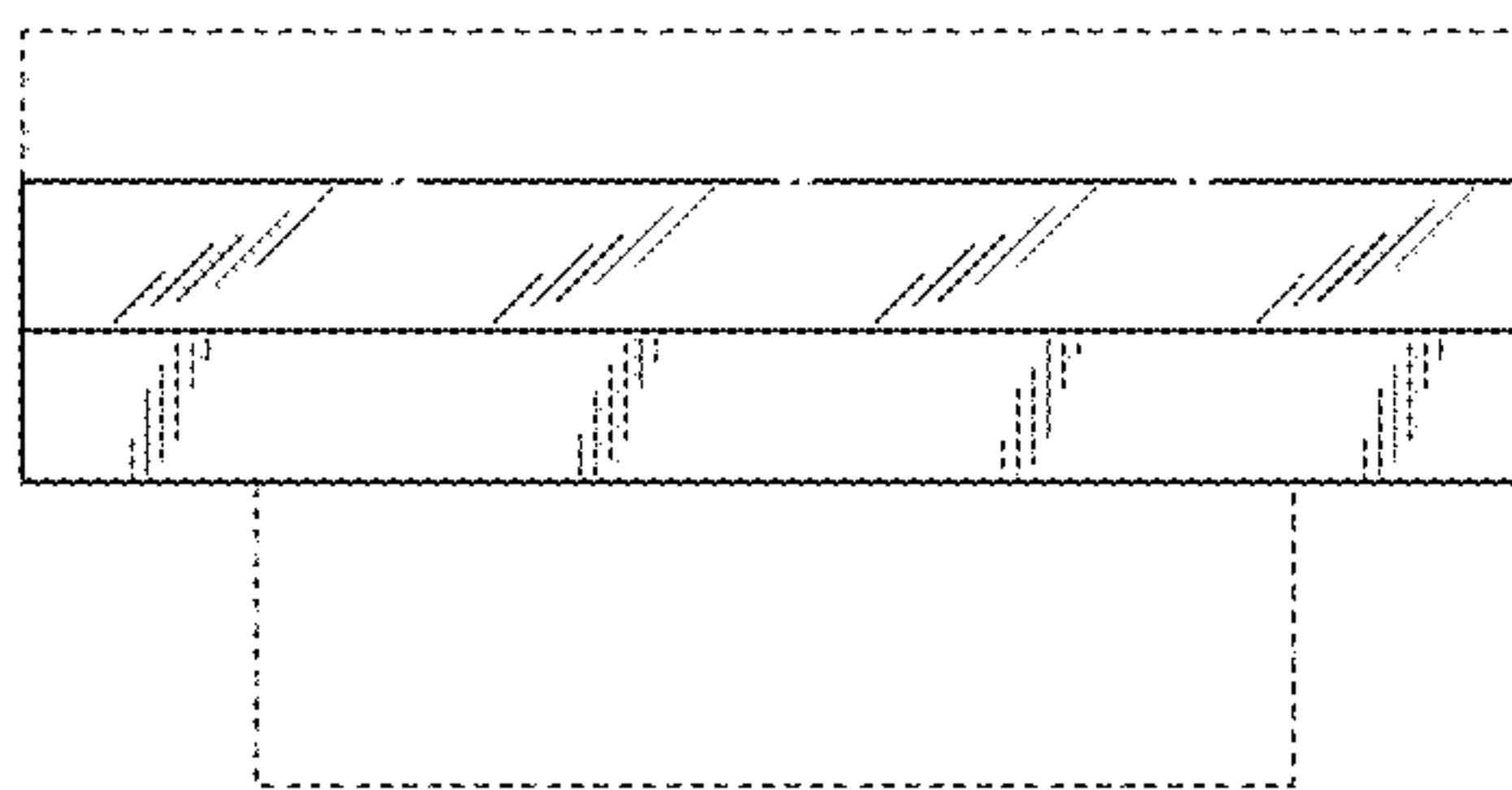


FIG. 4

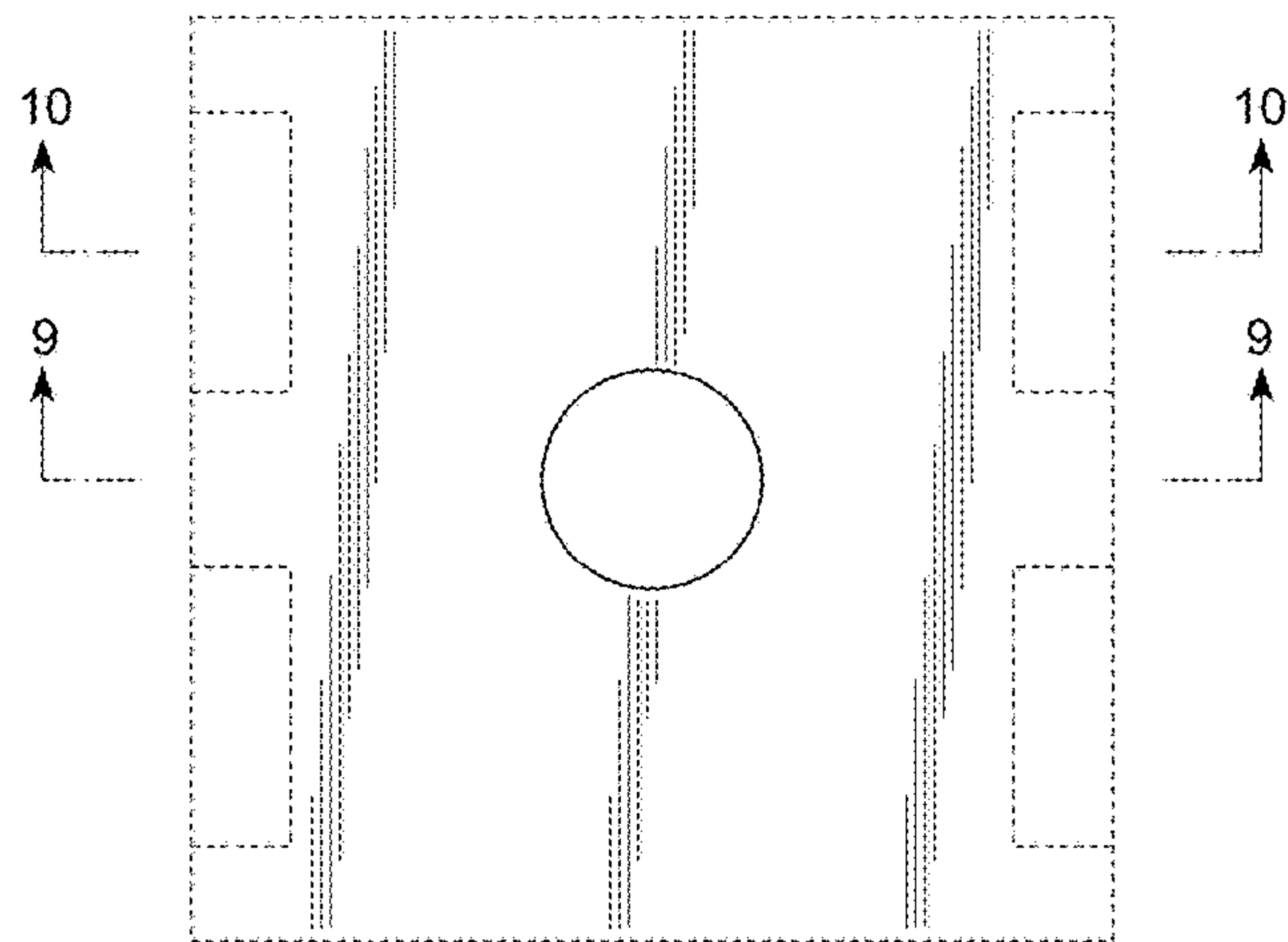


FIG. 5

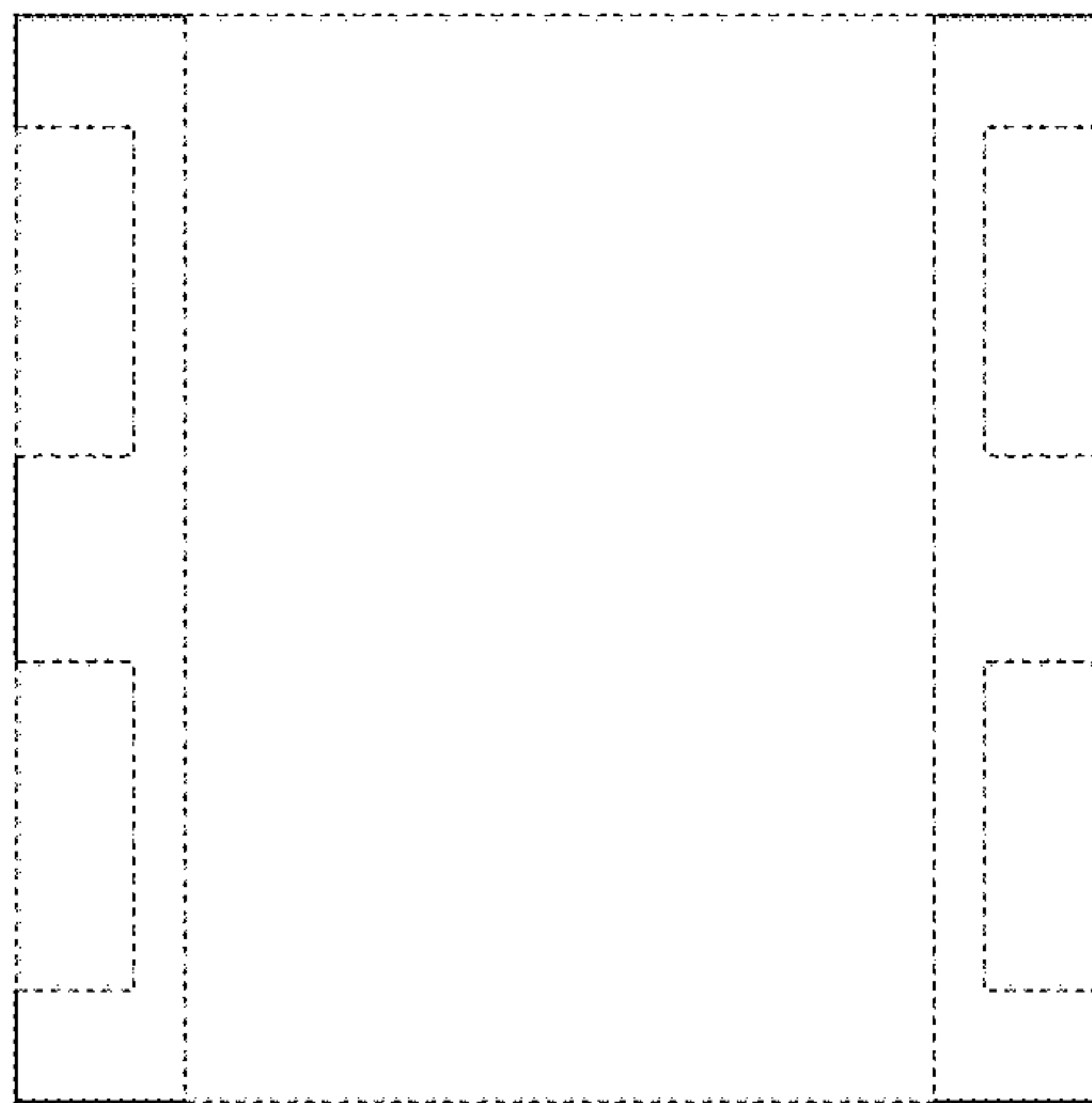


FIG. 6

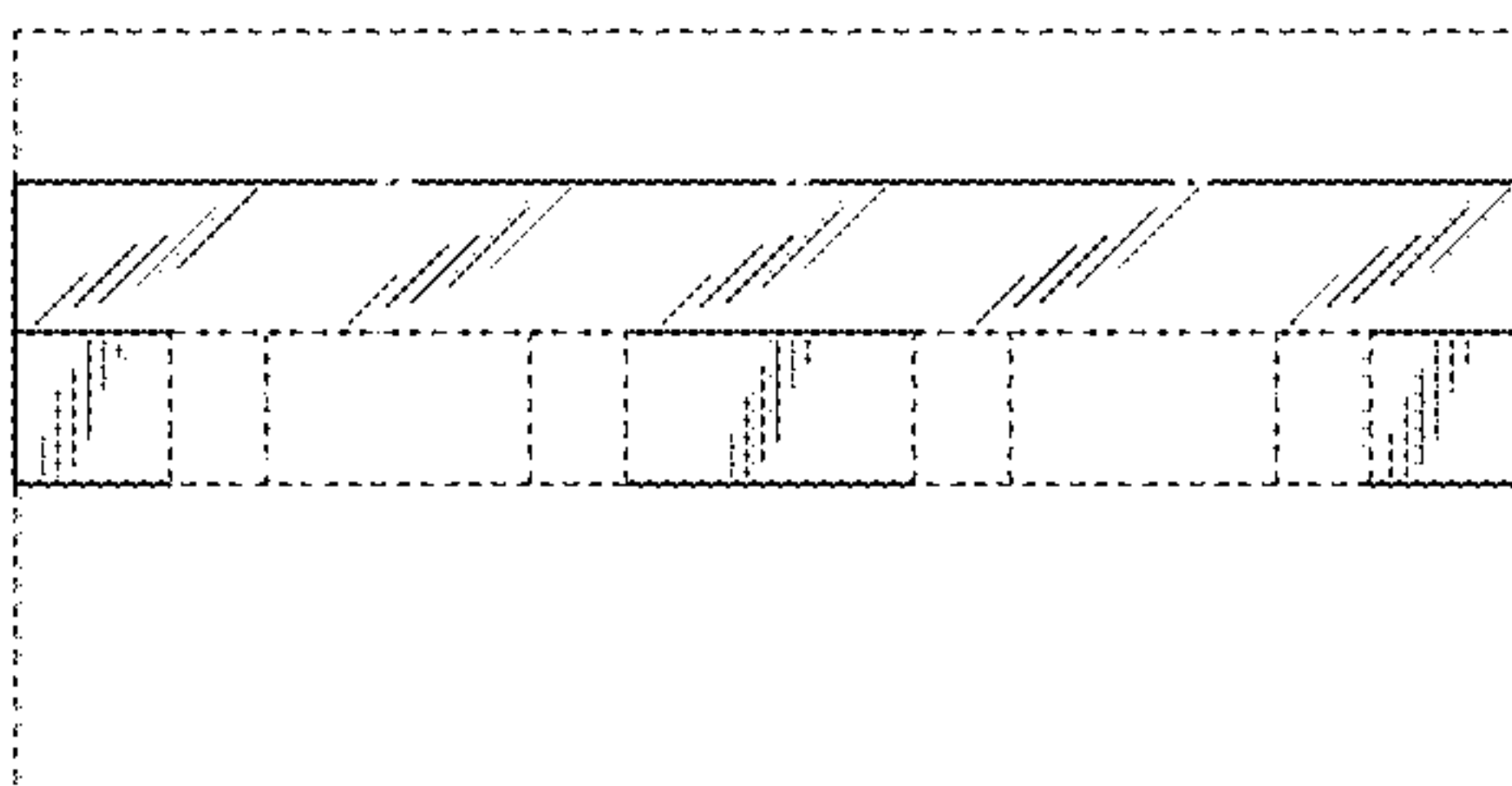


FIG. 7

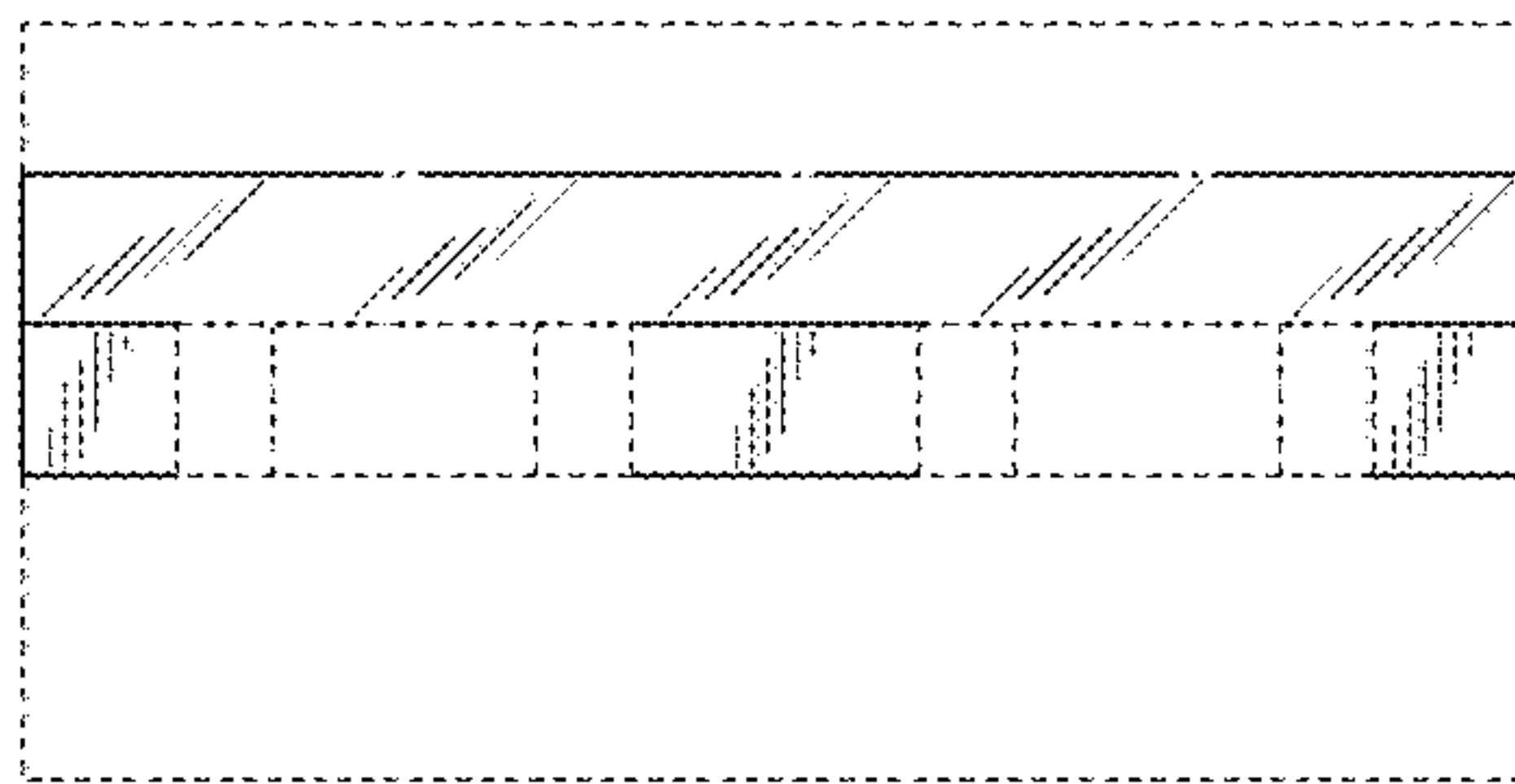


FIG. 8

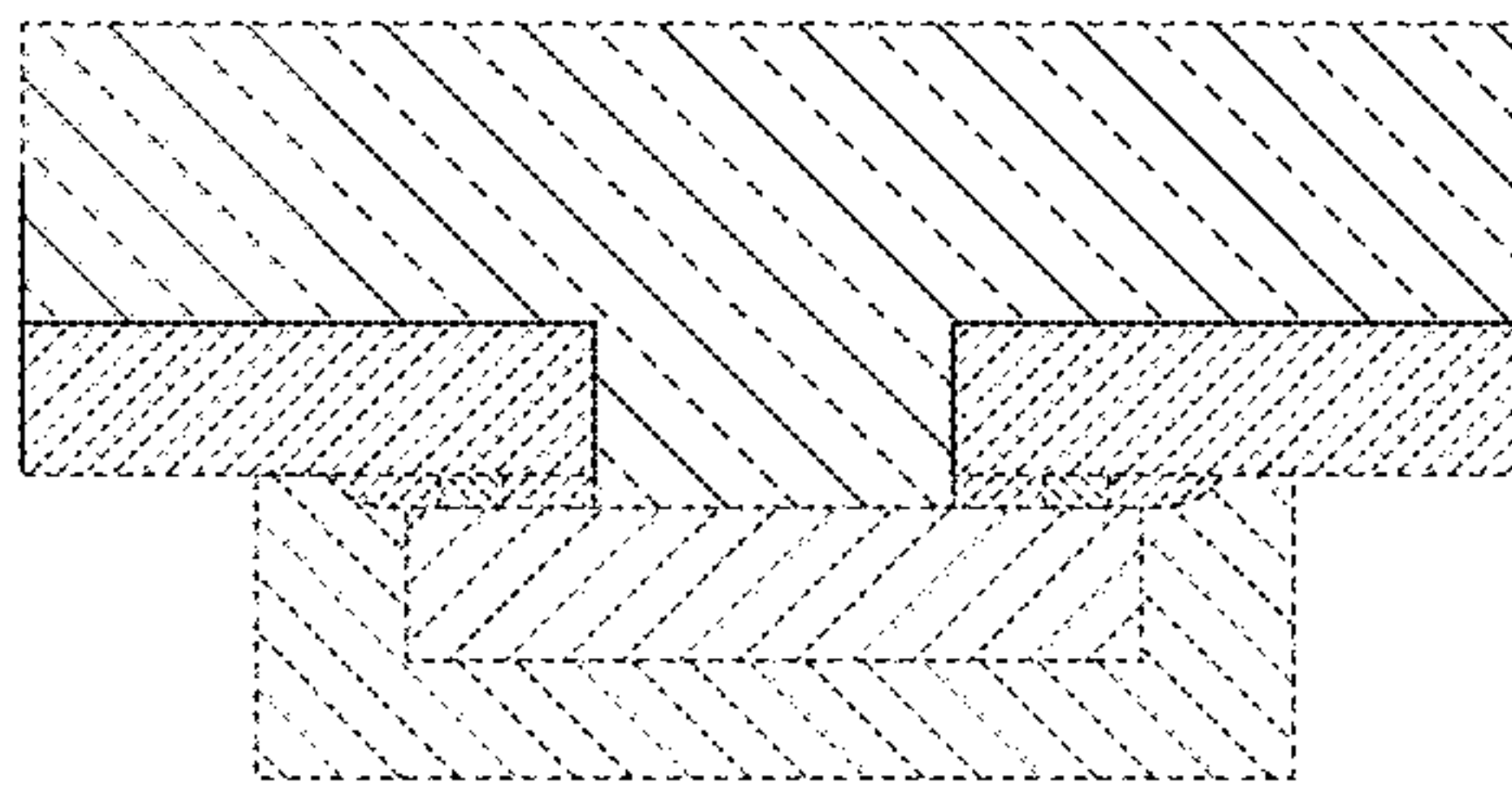


FIG. 9

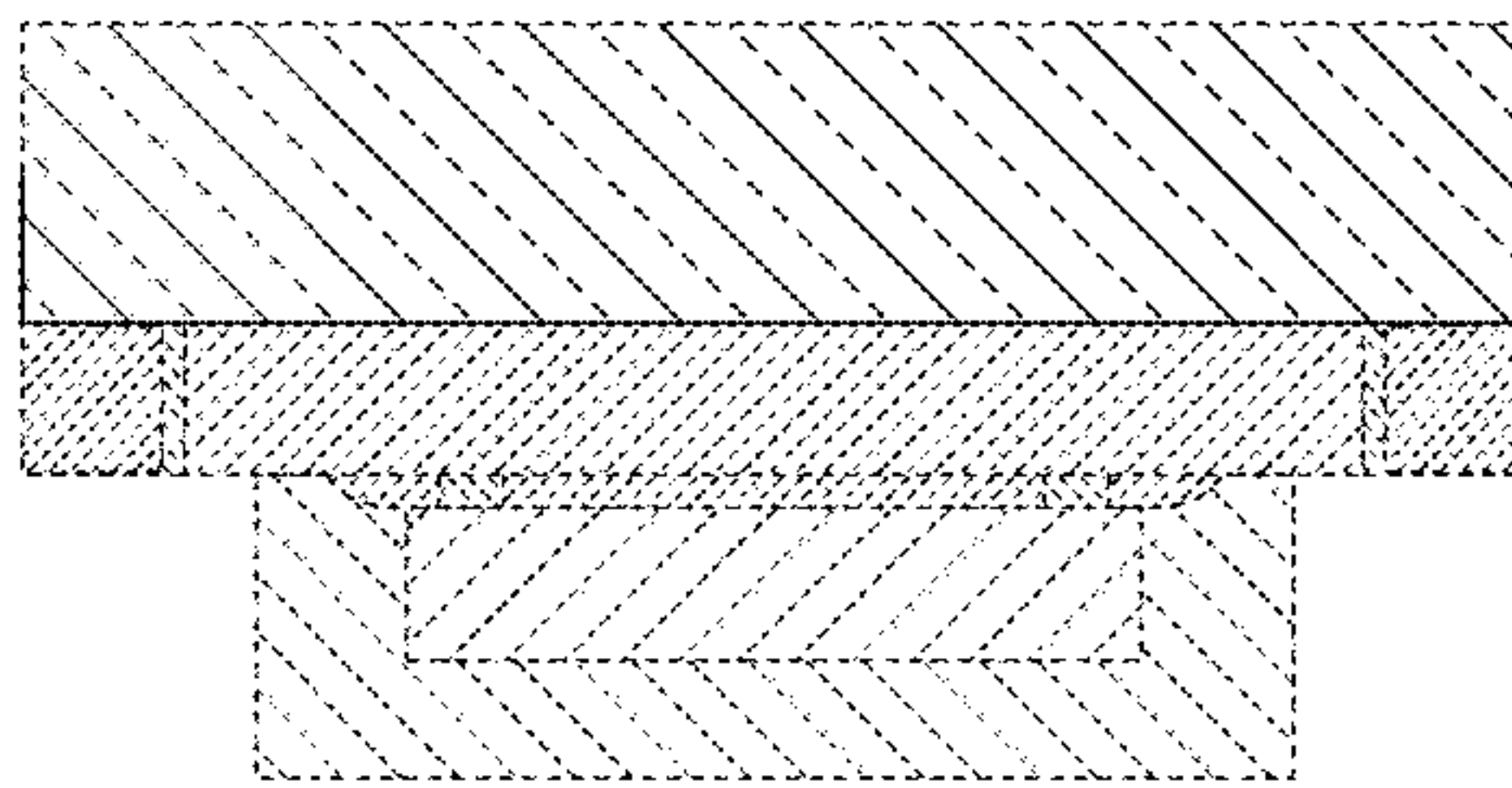


FIG. 10

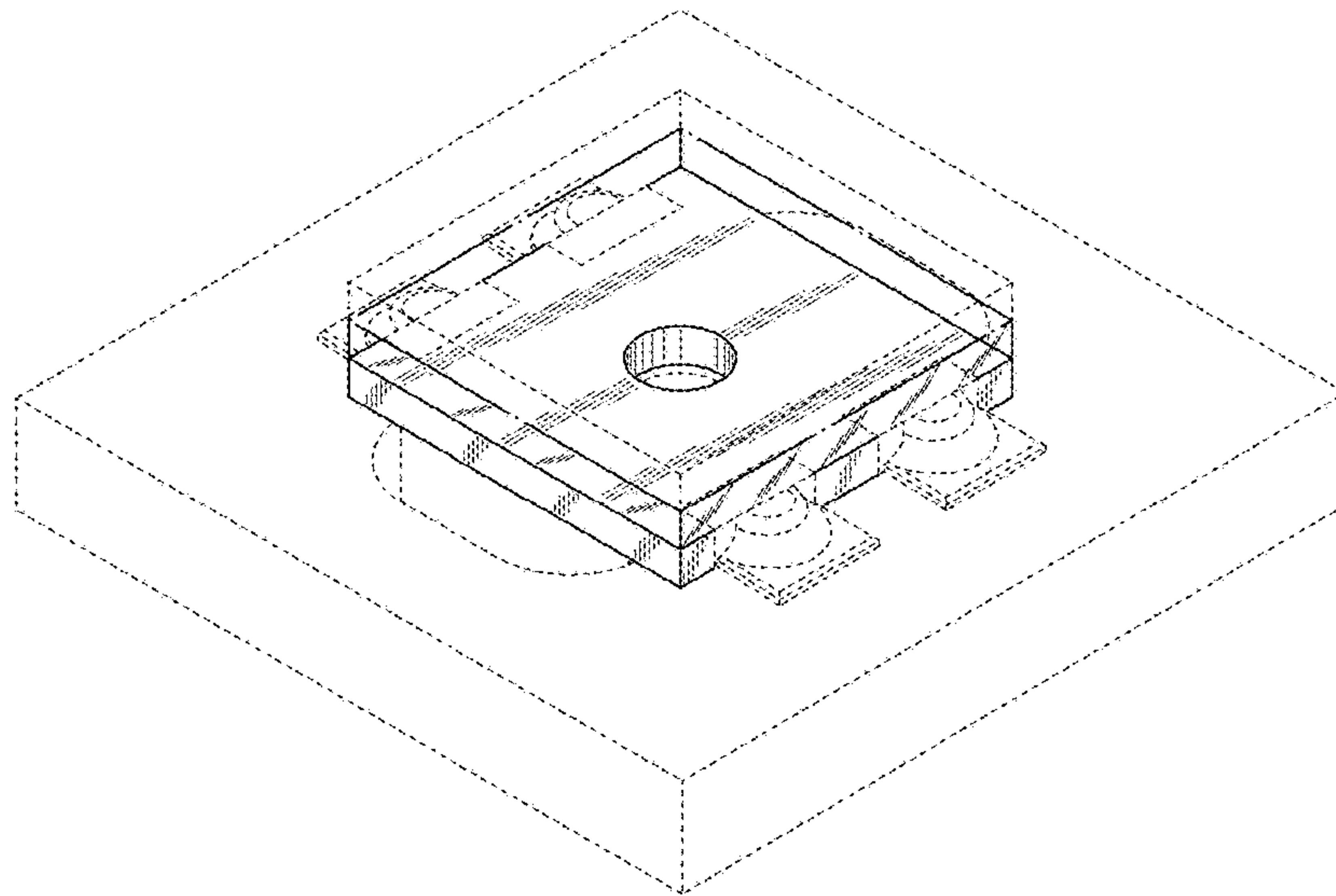


FIG. 11